

Product Change Notification / LIAL-15QFEX833

Date:

21-Jul-2021

Product Category:

Microphone Preamplifiers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4733 Initial Notice: Qualification of UAT as a new bumping site for AAP803A1 and AAP803A3 Microsemi catalog part numbers (CPN) available in 6L WLCSP (0.84x0.57x0.35mm) package.

Affected CPNs:

LIAL-15QFEX833_Affected_CPN_07212021.pdf LIAL-15QFEX833_Affected_CPN_07212021.csv

Notification Text:

PCN Status: Initial notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of UAT as a new bumping site for AAP803A1 and AAP803A3 Microsemi catalog part numbers (CPN) available in 6L WLCSP (0.84x0.57x0.35mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
Bumping Site	Packaging Technologies (PACTECH) USA (PTUS)	Unisem Advance Tech (UAT)

Solder Ball Material	SAC 405	SAC 405			
Solder Ball Pitch	300um	300um			
Solder Ball Size	120um	120um			
UBM Deposition Method	Electroless Ni/Au plating	Sputter + Plated			
UBM Thickness	Ni/Au 5 um	0.1um Ti(sp.) + 0.2um Cu(sp.) + 8.6um Cu (pl.)			

Impacts to Data Sheet:None

Change Impact:None

Reason for Change: To improve manufacturability by qualifying UAT as new bump site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date: February 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	July 2021				>	February 2022					
Workweek	27	28	29	30	31		06	07	08	09	10
Initial PCN Issue Date				Х							
Qual Report Availability							Х				
Final PCN Issue Date							Х				

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: July 21, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-15QFEX833_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-15QFEX833 - CCB 4733 Initial Notice: Qualification of UAT as a new bumping site for AAP803A1 and AAP803A3 Microsemi catalog part numbers (CPN) available in 6L WLCSP (0.84x0.57x0.35mm) package.

Affected Catalog Part Numbers (CPN)

AAP803A1 AAP803A3